

H-997

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of

T. DANNO et al.

Group Art Unit: 2823

Serial No. 09/910,833

Examiner: F. Toledo

Filed: July 24, 2001

For: A SEMICONDUCTOR DEVICE MANUFACTURING METHOD WHEREIN

ELECTRODE MEMBERS ARE EXPOSED FROM A MOUNTING SURFACE OF A RESIN ENCAPSULATOR (As Amended)

REQUEST TO CORRECT NOTICE OF ALLOWANCE

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

L August 3,22004

Sir:

Please correct the Notice of Allowance mailed July 12, 2004 as follows:

In the title, please change "SEMICONDUCTOR DEVICE

ANUFACTURING METHOD WHEREIN ELECTRODE MEMBERS ARE EXPOSED FROM

A MOUNTING SURFACE OF A RESIN ENCAPSULATOR" TO --Semiconductor

Device Manufacturing Method Wherein Electrode Members are

Exposed From a Mounting Surface of a Resin Encapsulator--.

In addition, Applicants respectfully request that the Examiner acknowledge the Information Disclosure Statement and PTO Form 1449 filed on December 16, 2003 on the corrected Notice of Allowability.

The undersigned requests that a corrected Notice of Allowance be issued.

Respectfully submitted,

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